

N-Channel Enhancement Mode MOSFET

1. Product Information

Features

- Advanced Technology
- Excellent $R_{DS(ON)}$, Low gate charge

Applications

- Battery protection
- Load switch
- Uninterruptible power supply

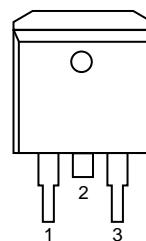
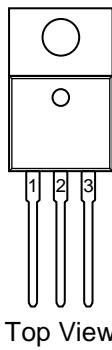
Quick reference

$B_V = 60V$
 $I_D = 130A$
 $R_{DS(ON)} \leq 3.5m\Omega @ V_{GS}=10V$ (Type:2.8 mΩ)

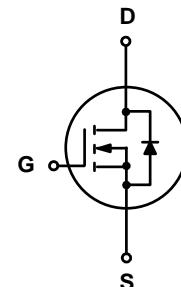
Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

Simplified Outline



Symbol



Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape width	Quantity
KJ130N06C	TO-220	130N06 YWWXXX			800
KJ130N06D	TO-263	YWWXXX Date Code			1000

2. Absolute Maximum Ratings (TC=25°C unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
VGS	Gate-Source Voltage	± 20	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current ^{1,6}	130	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current ^{1,6}	66	A
IDM	Pulsed Drain Current ²	240	A
EAS	Single Pulse Avalanche Energy ³	101	mJ
IAS	Avalanche Current	130	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	168	W
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	60	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	1.5	°C/W

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	67		V
IDSS	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$			1	μA
IGSS	Gate-Body Leakage Current	$V_{\text{GS}}= \pm 20\text{V}, V_{\text{DS}}=0\text{V}$			± 100	nA
$\text{VGS}(\text{th})$	Gate Threshold Voltage	$V_{\text{DS}}= V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.8	2.5	V
RDS(ON)	Static Drain-Source On-Resistance	$V_{\text{GS}}= 10\text{V}, I_{\text{D}}=20\text{A}$		2.8	3.5	$\text{m}\Omega$
		$V_{\text{GS}}= 4.5\text{V}, I_{\text{D}}=15\text{A}$		3.2	4.0	
C_{iss}	Input Capacitance	$V_{\text{DS}}=25\text{V}, V_{\text{GS}}=0\text{V}, f=100\text{KHZ}$		5950		pF
C_{oss}	Output Capacitance			1250		
C_{rss}	Reverse Transfer Capacitance			85		
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=50\text{A}$		93		nC
Q_{gs}	Gate-Source Charge			17		
Q_{gd}	Gate-Drain Charge			14		
Q_{rr}	Reverse Recovery Chrage	$I_F=25\text{A}, dI/dt=100\text{A/us}$		73		nC
t_{rr}	Reverse Recovery Time			68		
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{GS}}=10\text{V}, V_{\text{DD}}=30\text{V}, I_{\text{D}}=25\text{A}$ $R_{\text{GEN}}=2\Omega$		22.5		ns
t_r	Turn-on Rise Time			6.7		
$t_{\text{d(off)}}$	Turn-off Delay Time			80.3		
t_f	Turn-off fall Time			26.9		
V_{SD}	Diode Forward Voltage	$I_{\text{S}}=20\text{A}, V_{\text{GS}}=0\text{V}$			1.2	V
I_{S}	Maximum Body-Diode Continuous Current				200	A

Note :

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3、The EAS data shows Max. rating . The test condition is $V_{\text{DD}}=48\text{V}, V_{\text{GS}}=10\text{V}, L=0.1\text{mH} I_{\text{AS}}=130\text{A}$
- 4、The power dissipation is limited by 150°C junction temperature
- 5、The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation

4.Typical Characteristics

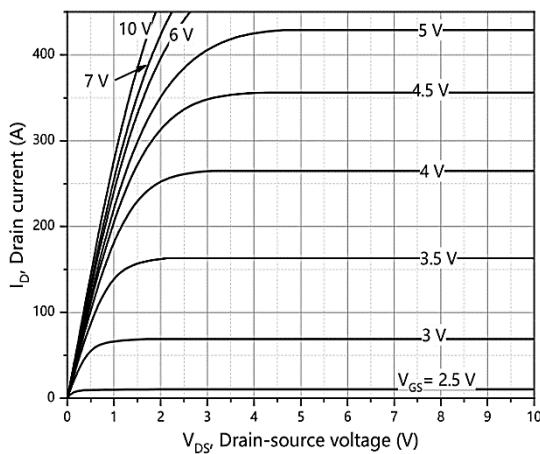


Figure 1. Typ. output characteristics

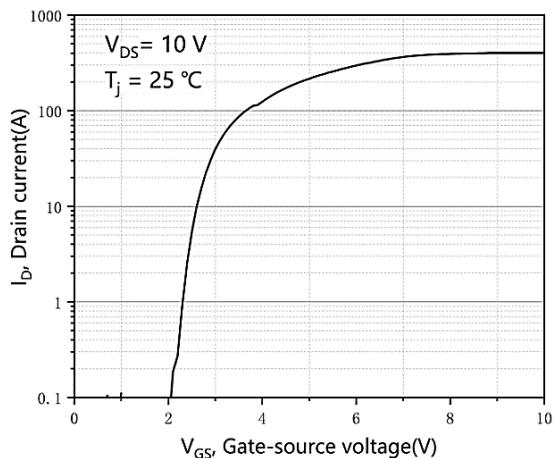


Figure 2. Typ. transfer characteristics

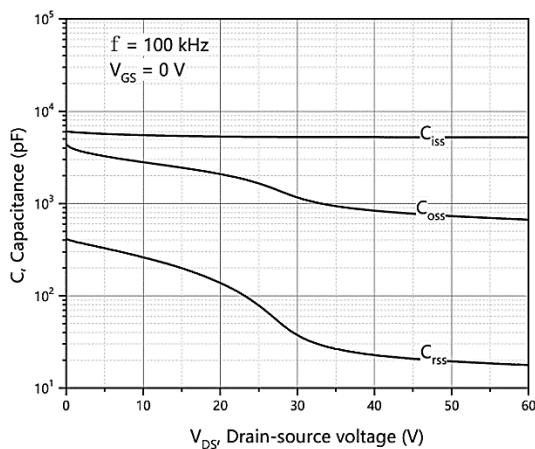


Figure 3. Typ. capacitances

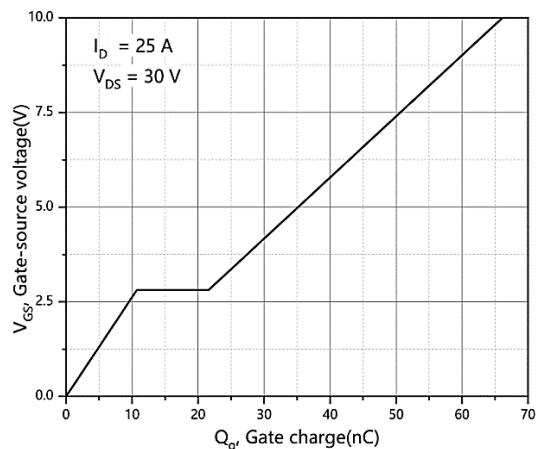


Figure 4. Typ. gate charge

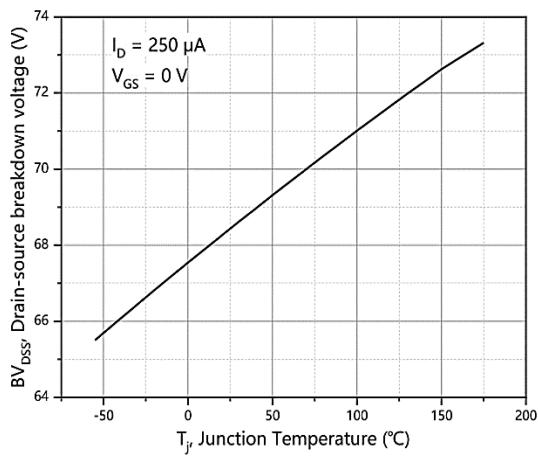


Figure 5. Drain-source breakdown voltage

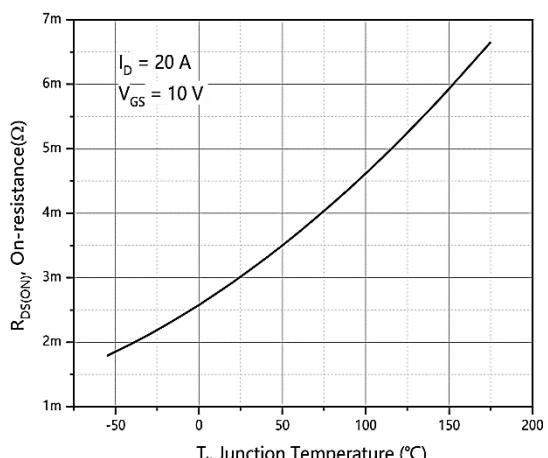


Figure 6. Drain-source on-state resistance

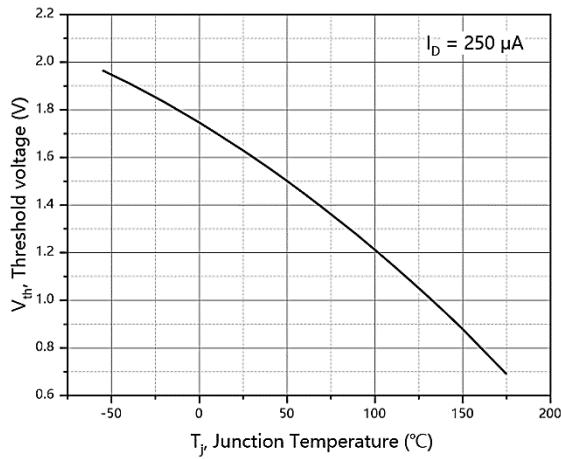


Figure 7. Threshold voltage

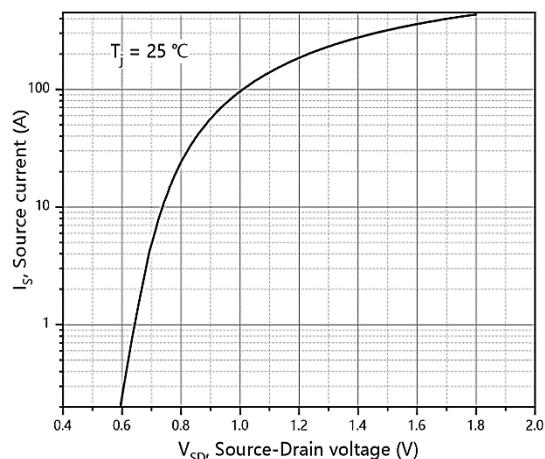


Figure 8. Forward characteristic of body diode

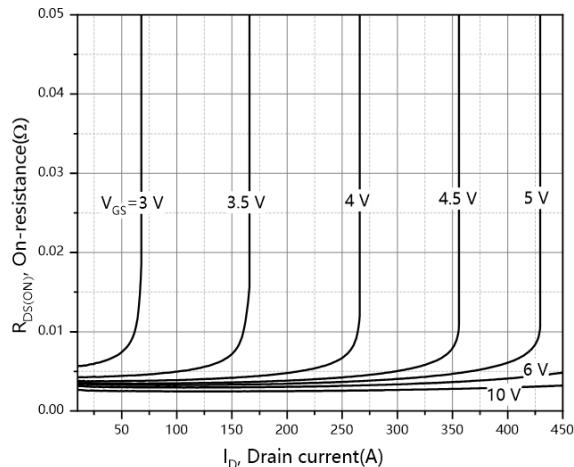


Figure 9. Drain-source on-state resistance

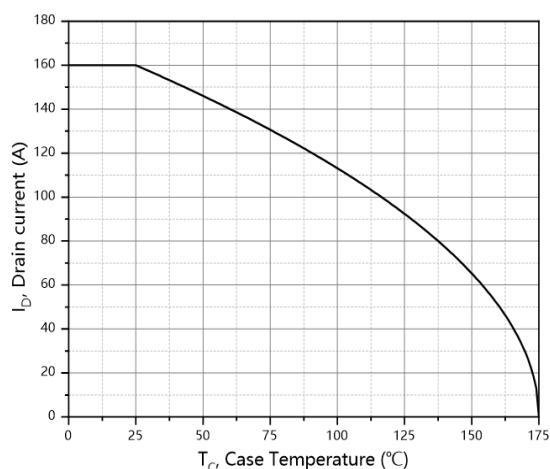


Figure 10. Drain current

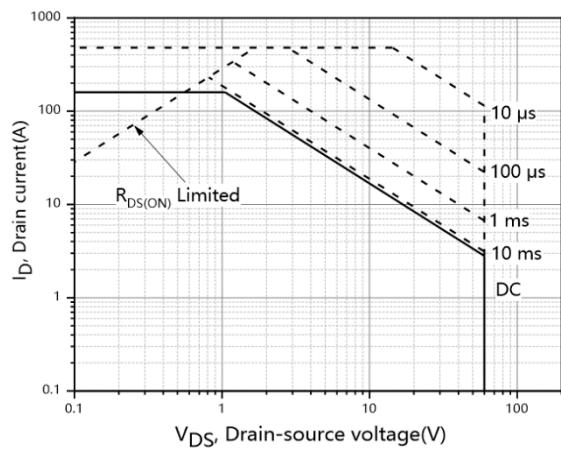


Figure 11. Safe operation area $T_c=25^\circ\text{C}$

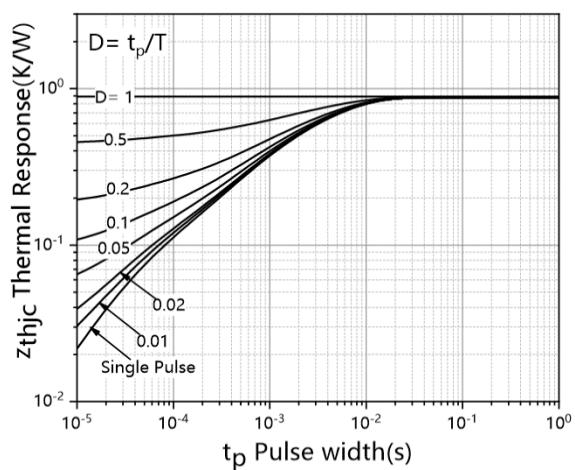
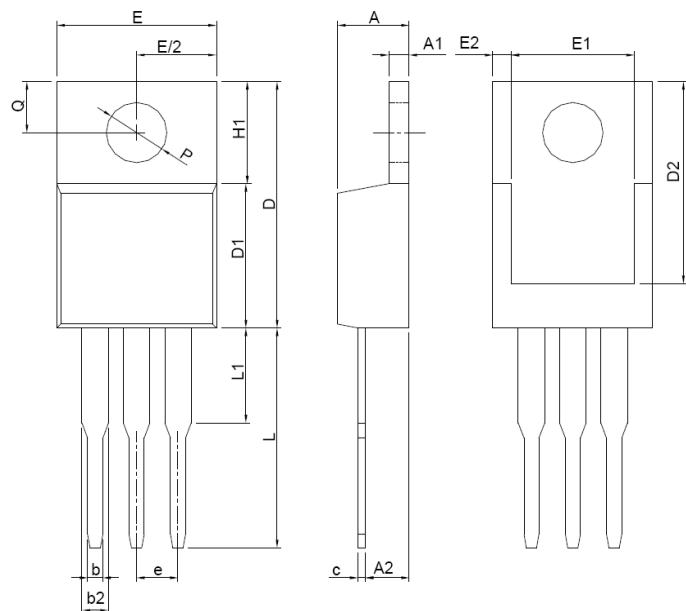


Figure 12. Max. transient thermal impedance

5.Package Mechanical Data

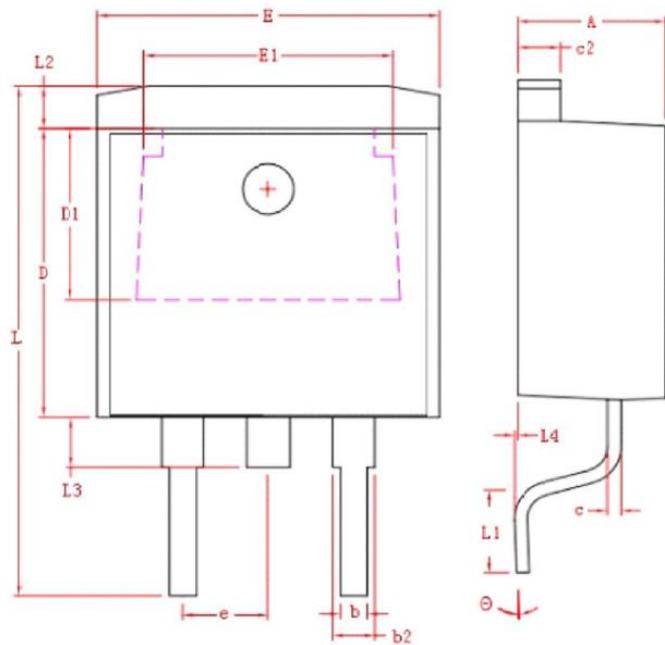
TO-220



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	3.56	4.83
A1	0.51	1.40
A2	2.03	2.92
b	0.38	1.02
b2	1.14	1.78
c	0.36	0.61
D	14.22	16.51
D1	8.38	9.02
D2	12.19	12.88
E	9.65	10.67
E1	6.86	8.89
E2	0.76BSC	
e	2.54BSC	
H1	5.84	6.86
L	12.70	14.73
L1	6.35BSC	
P	3.53	4.09
Q	2.54	3.43

5.Package Mechanical Data

TO-263



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	4.40	4.80
b	0.76	1.00
L4	0.00	0.25
C	0.36	0.50
L3	1.50 REF	
L1	2.29	2.79
E	9.80	10.40
E1	7.40 REF	
c2	1.25	1.45
b2	1.17	1.47
D	8.60	9.00
D1	5.10 REF	
e	2.54 REF	
L	14.6	15.8
θ	$0^\circ \pm 3^\circ$	
L2	1.27 REF	